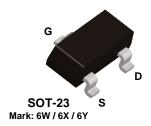


J174 J175 J176 **J177**  **MMBFJ175** MMBFJ176 MMBFJ177





### **P-Channel Switch**

This device is designed for low level analog switching sample and hold circuits and chopper stabilized amplifiers. Sourced from Process 88.

## **Absolute Maximum Ratings\***

TA = 25°C unless otherwise noted

| Symbol                           | Parameter  | Value       | Units |  |
|----------------------------------|--|-------------|-------|--|
| $V_{DG}$                         | Drain-Gate Voltage                               | - 30        | V     |  |
| $V_{GS}$                         | Gate-Source Voltage                              | 30          | V     |  |
| I <sub>GF</sub>                  | Forward Gate Current                             | 50          | mA    |  |
| T <sub>J</sub> ,T <sub>stg</sub> | Operating and Storage Junction Temperature Range | -55 to +150 | °C    |  |

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
  2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# **Thermal Characteristics**

TA = 25°C unless otherwise noted

| Symbol          | Characteristic                          | Max         |           | Units |
|-----------------|---|-------------|-----------|-------|
|                 |   | J174 - J177 | *MMBFJ175 |       |
| P <sub>D</sub>  | Total Device Dissipation                | 350         | 225       | mW    |
|                 | Derate above 25°C                       | 2.8         | 1.8       | mW/°C |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case    | 125         |           | °C/W  |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 357         | 556       | °C/W  |

<sup>\*</sup>Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

### P-Channel Switch

Max

Min

(continued)

**Units** 

### **Electrical Characteristics**

**Parameter** 

TA = 25°C unless otherwise noted

**Test Conditions** 

| B <sub>(BR)GSS</sub> | Gate-Source Breakdown Voltage | $I_G = 1.0 \mu\text{A},  V_{DS} = 0$               |      | 30  |     | V  |
|----------------------|-------------------------------|--|------|-----|-----|----|
| I <sub>GSS</sub>     | Gate Reverse Current          | $V_{GS} = 20 \text{ V}, V_{DS} = 0$                |      |     | 1.0 | nA |
| V <sub>GS(off)</sub> | Gate-Source Cutoff Voltage    | V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 10 nA | J174 | 5.0 | 10  | V  |
|                      |                               |  | J175 | 3.0 | 6.0 | V  |
|                      |                               |  | J176 | 1.0 | 4.0 | V  |
|                      |                               |  | J177 | 0.8 | 2.5 | V  |

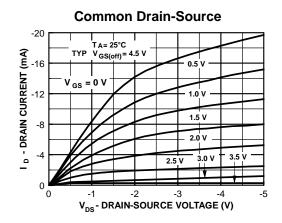
### ON CHARACTERISTICS

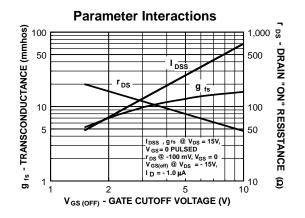
**Symbol** 

| I <sub>DSS</sub>    | Zero-Gate Voltage Drain Current* | $V_{DS} = -15 \text{ V}, I_{GS} = 0$   | J174 | - 20  | - 100 | mA |
|---------------------|----------------------------------|--|------|-------|-------|----|
|                     |                                  |  | J175 | - 7.0 | - 60  | mA |
|                     |                                  |  | J176 | - 2.0 | - 25  | mA |
|                     |                                  |  | J177 | - 1.5 | - 20  | mA |
| r <sub>DS(on)</sub> | Drain-Source On Resistance       | $V_{DS} \le 0.1 \text{ V}, V_{GS} = 0$ | J174 |       | 85    | Ω  |
| (,                  |                                  |  | J175 |       | 125   | Ω  |
|                     |                                  |  | J176 |       | 250   | Ω  |
|                     |                                  |  | J177 |       | 300   | Ω  |

<sup>\*</sup>Pulse Test: Pulse Width  $\leq 300 \,\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ 

# **Typical Characteristics**



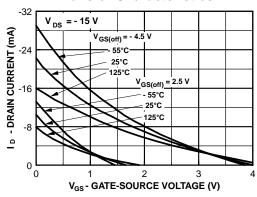


### **P-Channel Switch**

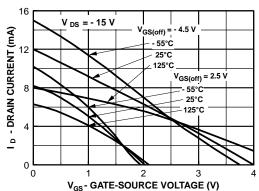
(continued)

# Typical Characteristics (continued)

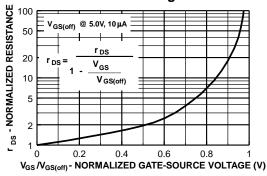




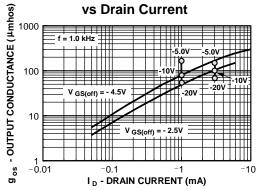
### **Transfer Characteristics**



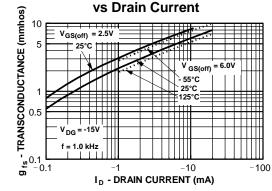
# Normalized Drain Resistance vs Bias Voltage



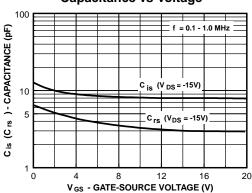
# Output Conductance



# Transconductance



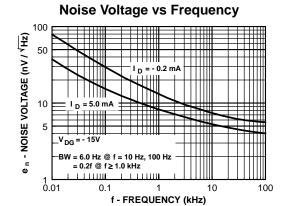
# Capacitance vs Voltage

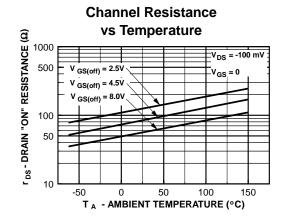


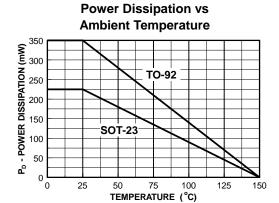
### P-Channel Switch

(continued)

# Typical Characteristics (continued)







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|--------------------------|---------------------------|---|
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